

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings of claims in the application:

**Listing of Claims:**

1                   1.       (Original) An apparatus for testing a packaged integrated circuit of the  
2 type incorporating a radiation sensing element comprising: a load board provided with electrical  
3 circuitry for interfacing with the packaged integrated circuit to be tested; a test socket, said test  
4 socket being mounted on said load board and being adapted to provide electrical connections  
5 between said packaged integrated circuit and said load board; a plunger for retaining said  
6 packaged integrated circuit within said test socket; and a radiation source mounted on said load  
7 board adjacent to said test socket wherein a radiation pathway is provided in said plunger, said  
8 pathway directing radiation emitted by said radiation source through said plunger to the radiation  
9 sensing element of said packaged integrated circuit.

1                   2.       (Original) An apparatus as claimed in claim 1 wherein the radiation  
2 pathway is a generally U-shaped pathway through the plunger.

1                   3.       (Currently Amended) An apparatus as claimed in claim 1 ~~or claim 2~~  
2 wherein a first end of the pathway is adjacent to the radiation source and a second end of the  
3 pathway is adjacent to the sensing element of the packaged integrated circuit when the plunger is  
4 used to retain the packaged integrated circuit within the test socket.

1                   4.       (Currently Amended) An apparatus as claimed in ~~any preceding~~ claim 1  
2 wherein said pathway is adapted for directing radiation from one end to its other end by the  
3 provision of radiation directing means.

1                   5.       (Original) An apparatus as claimed in claim 4 wherein the radiation  
2 directing means comprises two or more prisms mounted within the pathway.

1                   6.       (Original) An apparatus as claimed in claim 4 wherein the radiation  
2 directing means comprises a bundle of collimated optical fibres mounted within the pathway.

1                   7.       (Currently Amended) An apparatus as claimed in ~~any preceding~~ claim 1  
2 wherein the radiation source is operative to emit a radiation pattern which is directed to the  
3 radiation sensing element of the packaged integrated circuit via the pathway.

1                   8.       (Original) An apparatus as claimed in claim 7 wherein the radiation  
2 pattern comprises spatial and/or temporal variations in the intensity and/or frequency of radiation  
3 emitted by the radiation source.

1                   9.       (Currently Amended) An apparatus as claimed in claim 7 ~~or claim 8~~  
2 wherein the spatial position of the radiation pattern on the light source can be varied to  
3 compensate for minor misalignment between the plunger, the radiation source and the packaged  
4 integrated circuit.

1                   10.      (Currently Amended) An apparatus as claimed in ~~any preceding~~ claim 1  
2 wherein the area of the radiation source is equal to or greater than the cross-sectional area of the  
3 pathway.

1                   11.      (Currently Amended) An apparatus as claimed in ~~any preceding~~ claim 1  
2 wherein the cross-sectional area of the pathway is greater than or equal to the area of the sensing  
3 element of the packaged integrated circuit.

1                   12.      (Currently Amended) An apparatus as claimed in ~~any preceding~~ claim 1  
2 wherein the shape of the radiation source, cross-section of the pathway and the sensing element  
3 of the packaged integrated circuit are similar.

1                   13.      (Original) A method of testing packaged integrated circuits of the type  
2 incorporating a radiation sensing element comprising the following steps: inserting said  
3 packaged integrated circuit into a test socket, said test socket being mounted on a load board and

4 being adapted to provide electrical connections between said packaged integrated circuit and said  
5 load board wherein said load board is provided with electrical circuitry for interfacing with the  
6 packaged integrated circuit to be tested; retaining the packaged integrated circuit in the test  
7 socket by applying pressure with a plunger; and directing radiation from a radiation source  
8 mounted on said load board adjacent to said test socket through a radiation pathway provided in  
9 said plunger, thereby exposing the radiation sensing element to a suitable radiation signal emitted  
10 by the radiation emitting means.

1 14. (Currently Amended) A method as claimed in claim 13, wherein said  
2 pathway is adapted to direct radiation from one end to its other end by the provision of a  
3 radiation directing system ~~implemented using the apparatus of claims 1 to 13.~~

1 15. (New) The method of claim 14, wherein the radiation directing system  
2 includes two or more prisms positioned within the pathway.

1 16. (New) The method of claim 14, wherein the radiation directing system  
2 includes a bundle of collimated optical fibers located within the pathway.